

ABSTRACT OF THE DISCLOSURE

A ground electrode and a terminal electrode are formed on a first main surface of dielectric substrate forming a circuit board. Wiring electrodes are formed on a second main surface of the dielectric substrate. A semiconductor device and a filter are mounted on the wiring electrodes. A strip line electrode of the filter is connected to the ground electrode of the circuit board for conducting direct current, via a through-hole provided in the filter, a ground electrode of the filter, the wiring electrode, and a through-hole provided in the circuit board. With this arrangement, the terminal electrode is connected to a high-frequency signal terminal of the semiconductor device via the filter.